

-20V Pch+Pch Small Signal MOSFET

V _{DSS}	-20V
R _{DS(on)} (Max.)	215mΩ
I _D	±1.5A
P _D	1.25W

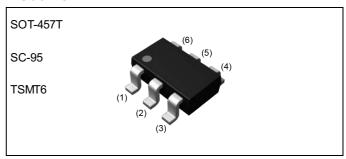
Features

- 1) Low on-resistance
- 2) Built-in G-S Protection Diode
- 3) Small Surface Mount Package (TSMT6)
- 4) Pb-free lead plating; RoHS compliant

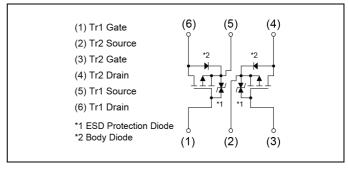
Application

Switching

Outline



Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Basic ordering unit (pcs)	3000
	Taping code	TR
	Marking	J01

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified) < Tr1 and Tr2>

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	-20	V
Continuous drain current	I _D	±1.5	Α
Pulsed drain current	I _{DP} *1	±6	Α
Gate - Source voltage	V_{GSS}	±12	V
Dower discinction (total)	P _D *2	1.25	\\/
Power dissipation (total)	P _D *3	0.95	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Downston	Cymahal	Values			1.1:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registeres innetion, embient (total)	R _{thJA} *2	-	-	100	°C/W
Thermal resistance, junction - ambient (total)	R _{thJA} *3	-	-	132	C/VV

●Electrical characteristics (T_a = 25°C) <Tr1 and Tr2>

Parameter	Cumbal	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = -1mA$	-20	-	-	V
Breakdown voltage	ΔV _{(BR)DSS}	I _D = -1mA		-18.7		mV/°C
temperature coefficient	ΔT_{j}	referenced to 25°C	1	-10.7	1	IIIV/ C
Zero gate voltage drain current	I _{DSS}	V _{DS} = -20V, V _{GS} = 0V		-	-1	μA
Gate - Source leakage current	I _{GSS}	I_{GSS} $V_{DS} = 0V$, $V_{GS} = \pm 12V$		-	±10	μA
Gate threshold voltage	V _{GS(th)}	$V_{GS(th)}$ $V_{DS} = -10V$, $I_D = -1mA$		-	-2.0	V
Gate threshold voltage	$\Delta V_{GS(th)}$	I _D = -1mA	_	2.3	_	mV/°C
temperature coefficient	ΔT_{j}	referenced to 25°C	- 2.3		-	IIIV/ C
		$V_{GS} = -4.5V, I_D = -1.5A$	ı	155	215	
Static drain - source on - state resistance	R _{DS(on)} *4	$V_{GS} = -4.0V, I_D = -1.5A$	1	170	235	mΩ
on take recipianies		V _{GS} = -2.5V, I _D = -0.75A	-	310	430	
Forward Transfer Admittance	Y _{fs} *4	V _{DS} = -10V, I _D = -0.75A	1.0	-	-	S

^{*1} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*2} Mounted on a ceramic board (30×30×0.8mm)

^{*3} Mounted on a FR4 (25×25×0.8mm)

^{*4} Pulsed

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

Darameter	Cymah al	Conditions	Values			Unit	
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Urill	
Input capacitance	C _{iss}	V _{GS} = 0V	-	270	-		
Output capacitance	C _{oss}	V _{DS} = -10V	-	40	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	35	-		
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq -15V, V_{GS} = -4.5V$	-	10	-		
Rise time	t _r *4	I _D = -0.75A	-	12	-		
Turn - off delay time	t _{d(off)} *4	$R_L = 20\Omega$	-	45	-	ns	
Fall time	t _f *4	$R_G = 10\Omega$	-	20	-		

ullet Gate charge characteristics (T_a = 25°C) <Tr1 and Tr2>

Parameter	Symbol Conditions		Values			Unit
raianietei	Symbol	Conditions	Min.	Тур.	Max.	Offit
Total gate charge	Q _g *4		-	3.0	-	
Gate - Source charge	Q _{gs} *4	$V_{DD} \simeq -15V, I_{D} = -1.5A$ $V_{GS} = -4.5V$	-	0.8	-	nC
Gate - Drain charge	Q _{gd} *4	193	-	0.85	-	

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

<Tr1 and Tr2>

Parameter	Symbol	Conditions	Values			Unit	
raianietei	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Continuous forward current	I _S	T - 25°C	-	-	-0.75	^	
Pulse forward current	I _{SP} *1	T _a = 25°C	-	-	-6	Α	
Forward voltage	V _{SD} *4	$V_{GS} = 0V, I_{S} = -0.75A$	-	-	-1.2	V	

Fig.1 Power Dissipation Derating Curve

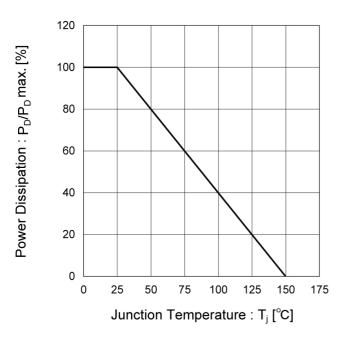
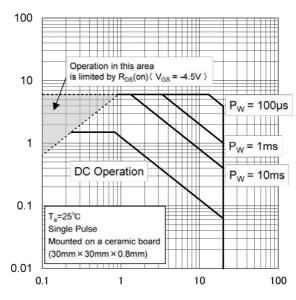


Fig.2 Maximum Safe Operating Area



Drain Current: -l_D [A]

Drain - Source Voltage : -V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

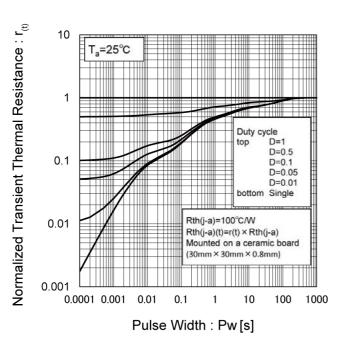


Fig.4 Single Pulse Maximum Power dissipation

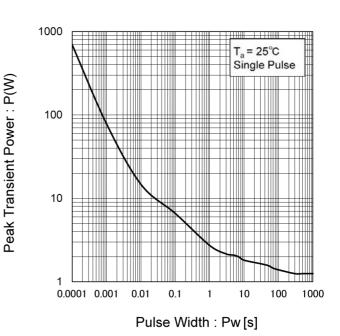


Fig.5 Typical Output Characteristics(I)

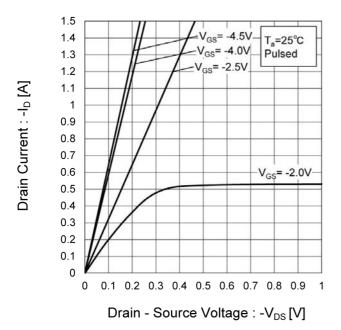


Fig.6 Typical Output Characteristics(II)

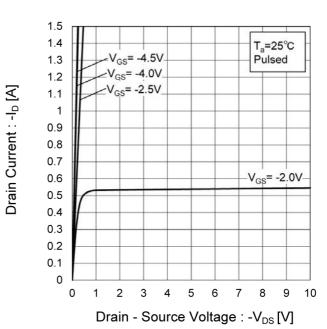
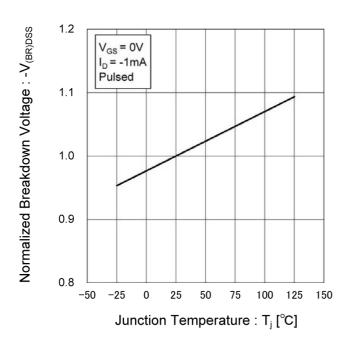


Fig.7 Breakdown Voltage vs.
Junction Temperature



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Fig.8 Typical Transfer Characteristics

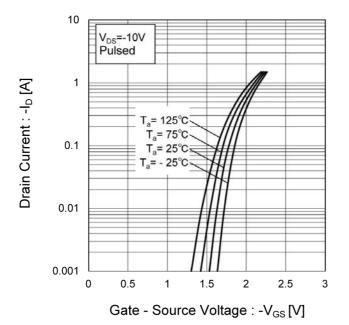


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

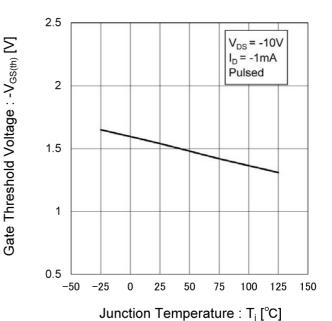




Fig.10 Drain Current Derating Curve

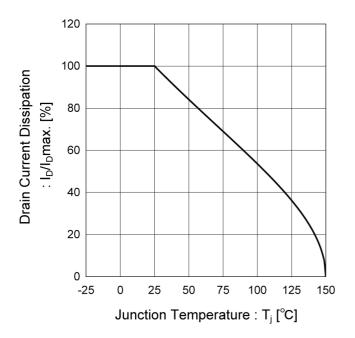


Fig.11 Static Drain - Source On - State Resistance vs. Gate Source Voltage

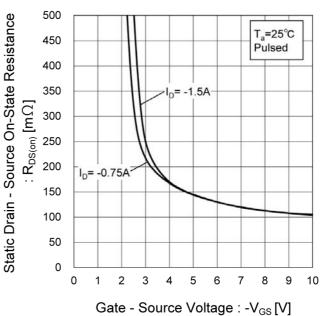


Fig.12 Static Drain - Source On - State Resistance vs. Junction Temperature

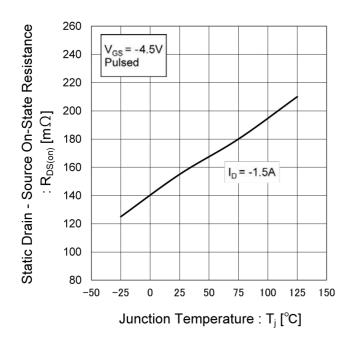


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current (I)

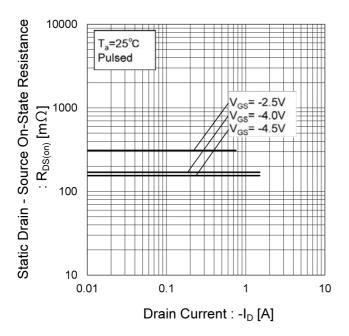


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (II)

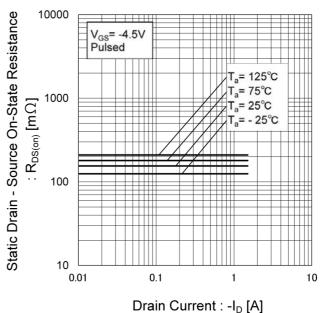


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (III)

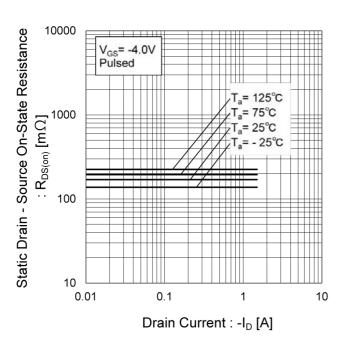


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (IV)

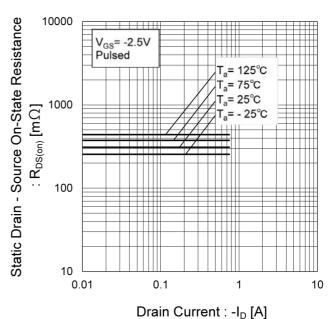


Fig.17 Typical Capacitance vs.

Drain - Source Voltage

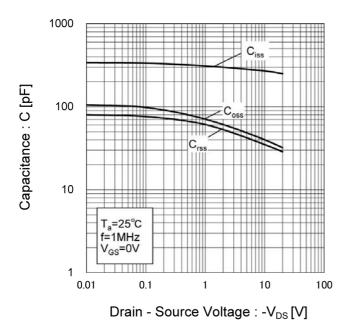


Fig.18 Switching Characteristics

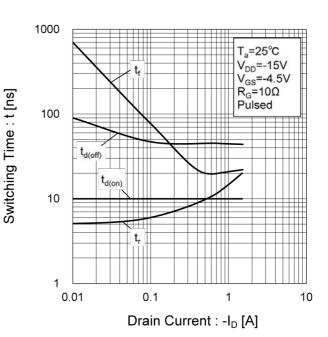


Fig.19 Dynamic Input Characteristics

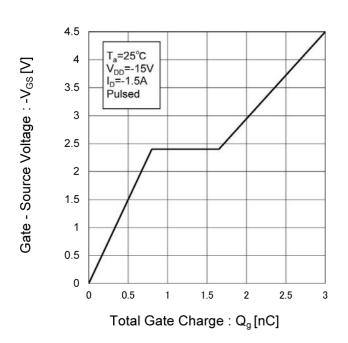
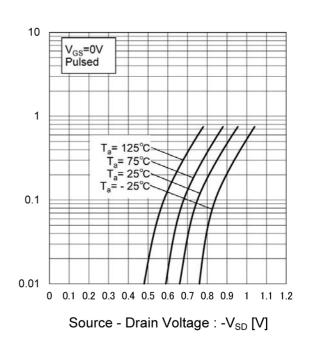


Fig.20 Source Current vs.

Source Drain Voltage



Source Current : -I_s [A]

• Measurement circuits < It is the same for the Tr1 and Tr2>

Fig.1-1 Switching Time Measurement Circuit

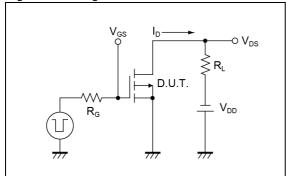


Fig.2-1 Gate Charge Measurement Circuit

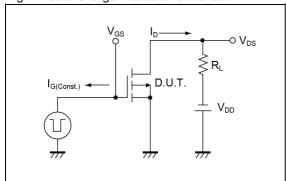


Fig.1-2 Switching Waveforms

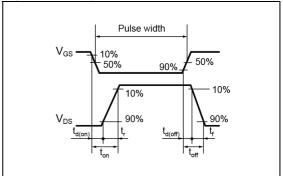
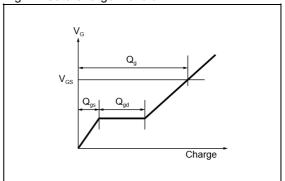


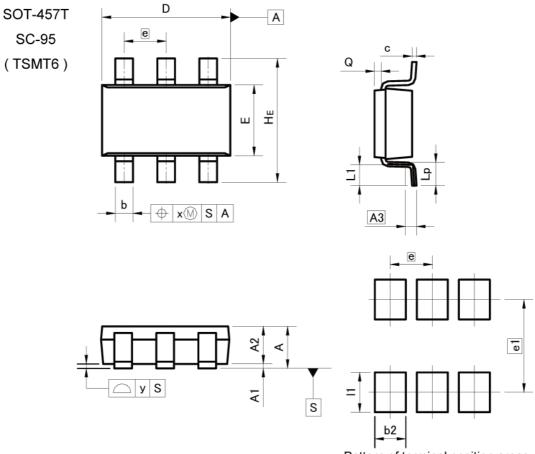
Fig.2-2 Gate Charge Waveform



Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	# =	1.00	=	0.039
A1	0.00	0.10	0.000	0.004
A2	0.75	0.95	0.030	0.037
A3	0.	25	0.0	10
b	0.35	0.50	0.014	0.020
С	0.10	0.26	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.	0.95		37
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.05	0.25	0.002	0.010
x	A-7	0.20	=:	0.008
У	()	0.10	-	0.004

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
b2		0.70	-	0.028
e1	2.	10	0.0	083
11	9. 	0.90	=1	0.035

Dimension in mm/inches



Notice

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSⅢ
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
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- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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Notice-PGA-E Rev.004

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